



Material Composition Declaration

EPC2015C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	2/6/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	12.2 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	10.5319	86.6694	88.9133	866694
	Silicon oxide	7631-86-9	0.0360	0.2959		2959
	Silicon nitride	12033-89-5	0.0126	0.1040		1040
	Gallium nitride	25617-97-4	0.0486	0.4002		4002
	Aluminum	7429-90-5	0.0849	0.6985		6985
	Aluminum nitride	24304-00-5	0.0103	0.0850		850
	Titanium	7440-32-6	0.0027	0.0225		225
	Titanium nitride	25583-20-4	0.0116	0.0958		958
	Copper	7440-50-8	0.0014	0.0117		117
	Tungsten	7440-33-7	0.0029	0.0237		237
	Polyimide		0.0616	0.5067	5067	
Under Bump Metal	Titanium	7440-32-6	0.0024	0.0195	0.0969	195
	Copper	7440-50-8	0.0094	0.0774		774
Solder Bump	Copper	7440-50-8	0.1176	0.9678	10.9898	9678
	Nickel	7440-02-0	0.0702	0.5773		5773
	Tin	7440-31-5	1.1270	9.2746		92746
	Silver	7440-22-4	0.0207	0.1700		1700
Sum in total:			12.1518	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.